

PICOSUN™ P-300B

The PICOSUN™ P-300B ALD system is specially designed for production of MEMS devices such as print heads, sensors, and microphones, and coating of 3D objects such as lenses, optics, mechanical parts, jewelry, coins, and medical implants.



Technical Features

The PICOSUN™ P-300 ALD systems have become the new standard in high volume ALD manufacturing. By integrating our patented hot-wall design with fully separated inlets, we can create the highest quality ALD films with excellent yield, low particle levels, and superior electrical and optical performance. The agile design with easy and fast maintenance ensures minimum system downtime and lowest cost-of-ownership in the market. Our proprietary Picoflow™ diffusion enhancer technology enables highly conformal coatings on ultra-high aspect ratio substrates with production-proven processes.

The PICOSUN™ P-300B ALD system is specially designed for batch processing in MEMS and 3-dimensional component production. The system is fast, highly reliable and extremely easy to maintain.

Typical substrate size and type

- 200 mm wafers in batches of 25 pcs (standard pitch)
- 150 mm wafers in batches of 50 pcs (standard pitch)
- 100 mm wafers in batches of 75 pcs (standard pitch)
- Non-wafer substrates (tailored holders)
- High aspect ratio samples (up to 1:2500)

Processing temperature

- 50 – 500°C

Typical processes

- Batch processes available with cycle times down to single digit seconds*
- Al_2O_3 , SiO_2 , Ta_2O_5 , HfO_2 , ZnO , TiO_2 , ZrO_2 , AlN , TiN , and metals
- Down to <1% 1σ non-uniformity in a batch (Al_2O_3 , WIW, WTW, B2B, 49 pts, 5mm EE)**

Substrate loading

- Manual loading with a pneumatic lift
- Linear semi-automatic loading
- Industrial robot loading

Precursors

- Liquid, solid, gas, ozone
- Level sensors, cleaning and refill service
- Up to 8 sources with 4 separate inlets

Please feel free to contact us for more information or a quotation!

* < 10s cycle time

** < 1% non-uniformity

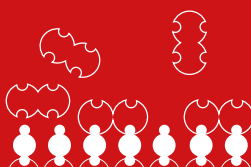
THE PRINCIPLE OF ALD



Introduction of molecules
containing element A.



Adsorption of the molecules
on the surface.



Introduction of molecules
containing element B and
reaction with element A on
the surface.



Completion of one
monolayer of compound AB.

Repeat cycle till desired film
thickness is reached.

picosun
AGILE ALD

Picosun HQ

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